

QUAD FLAT NO-LEAD (QFN) GRID ARRAY PACKAGE,
METHOD OF MAKING AND MEMORY MODULE AND
COMPUTER SYSTEM INCLUDING SAME

Inventors: Setho Sing Fee et al.

Filed: December 5, 2003

Attorney Docket No. 4738.1US

1/5

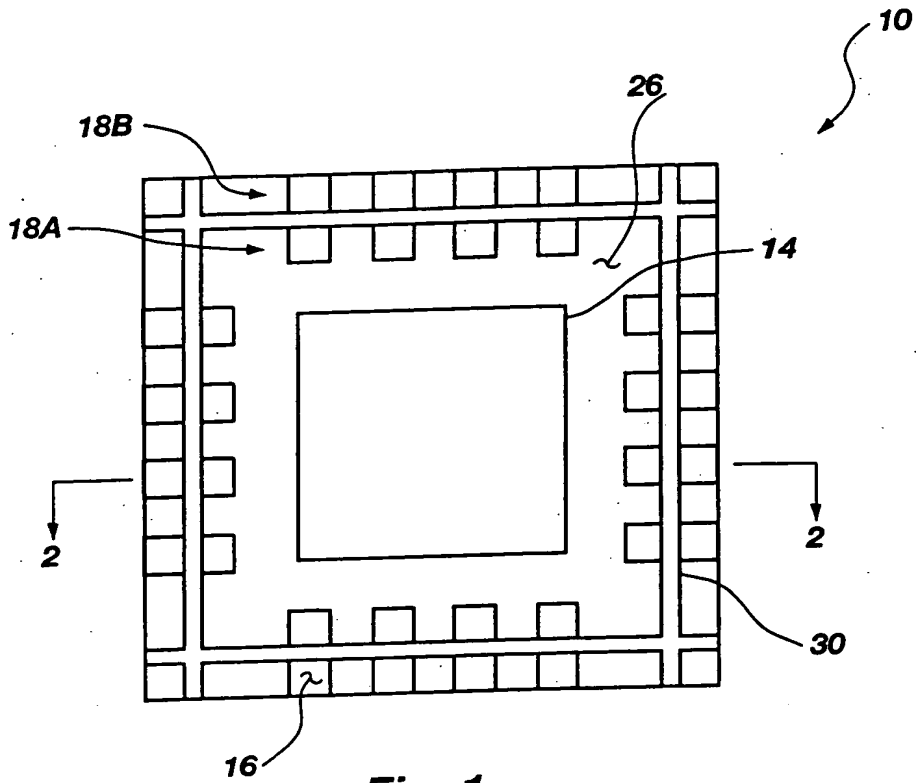


Fig. 1

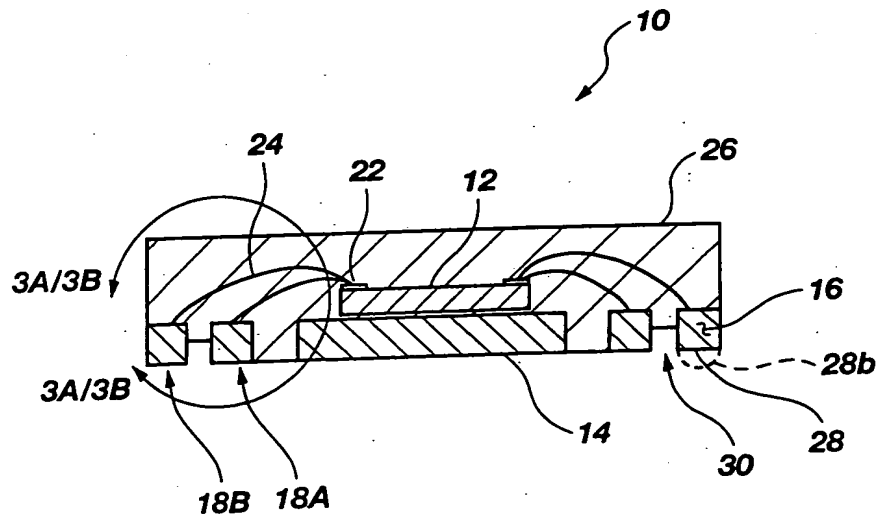


Fig. 2

QUAD FLAT NO-LEAD (QFN) GRID ARRAY PACKAGE,
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2/5

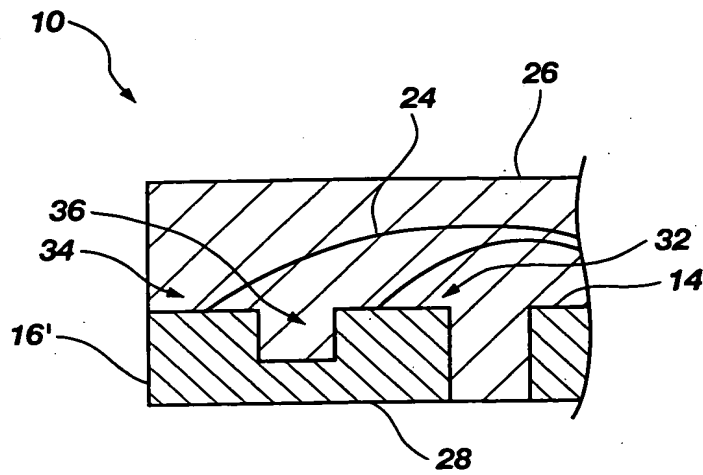


Fig. 3A

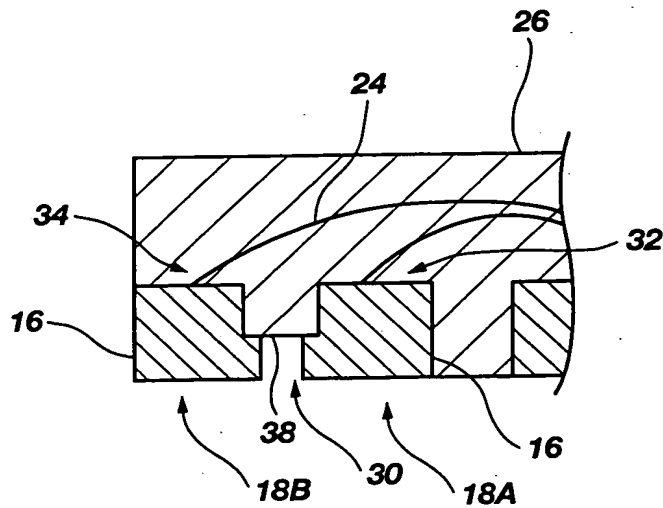


Fig. 3B

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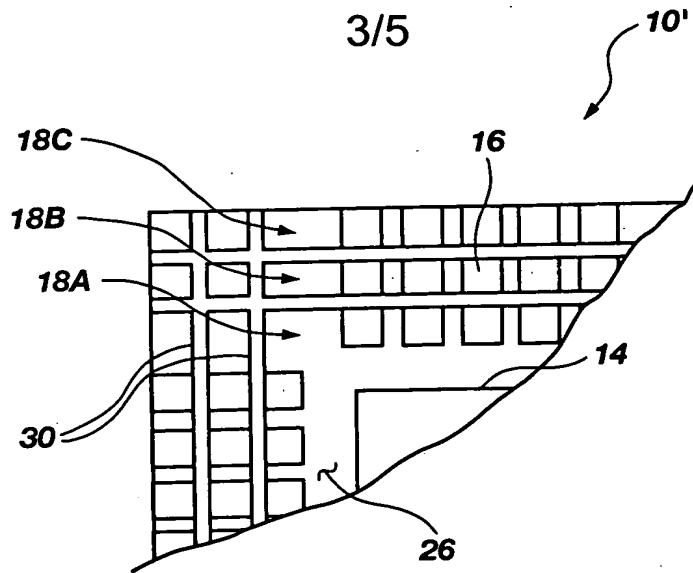


Fig. 4A

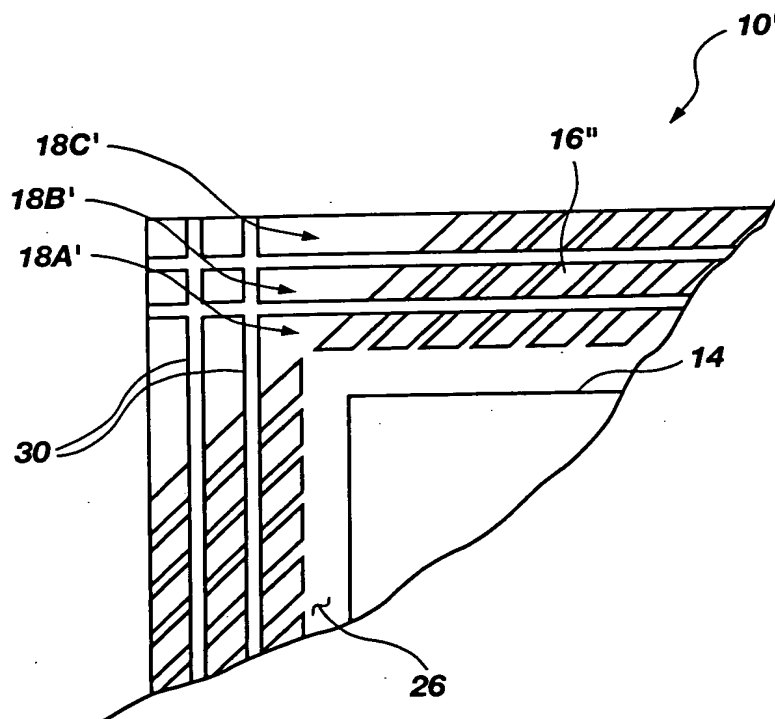


Fig. 4B

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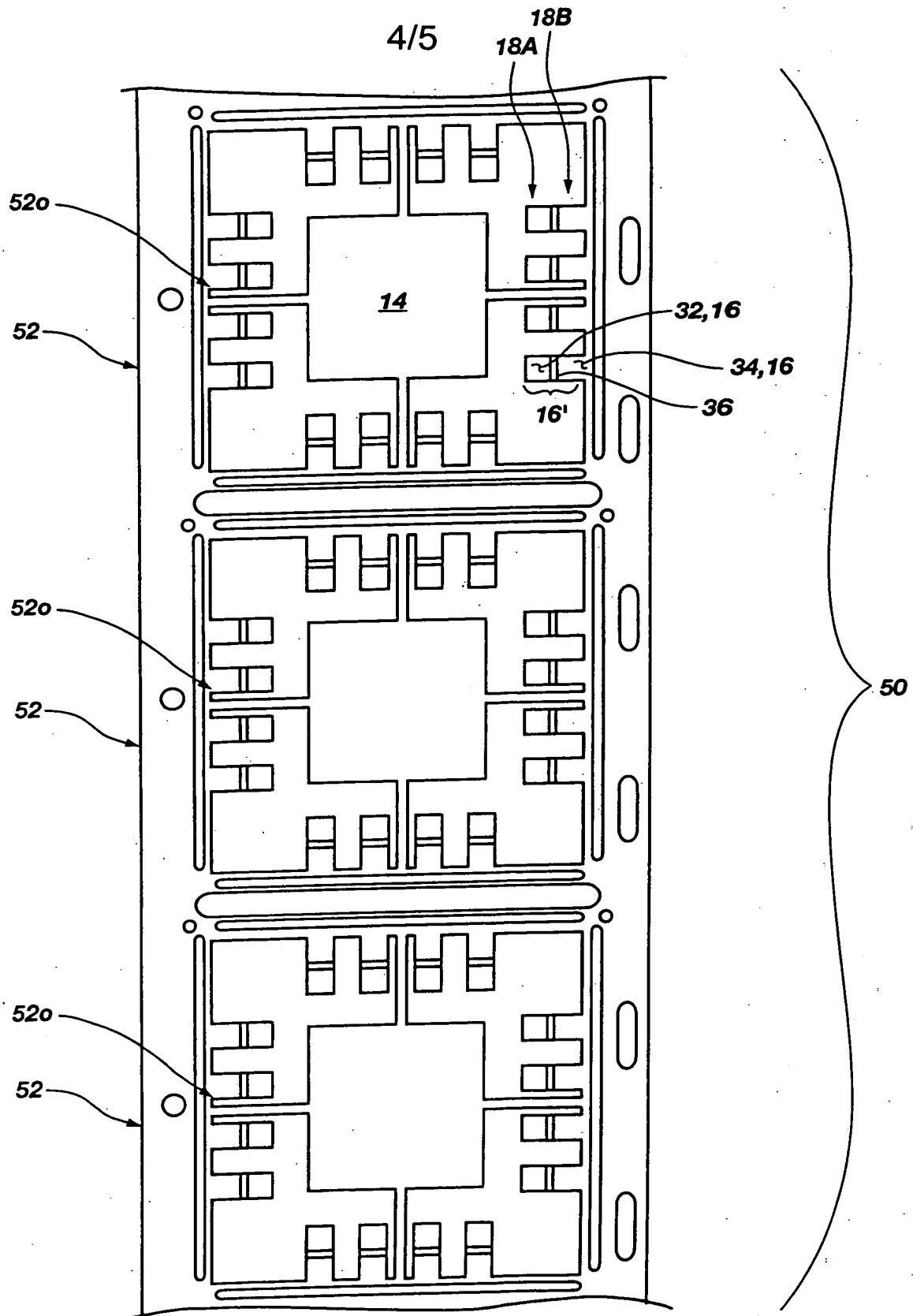


Fig. 5

5/5

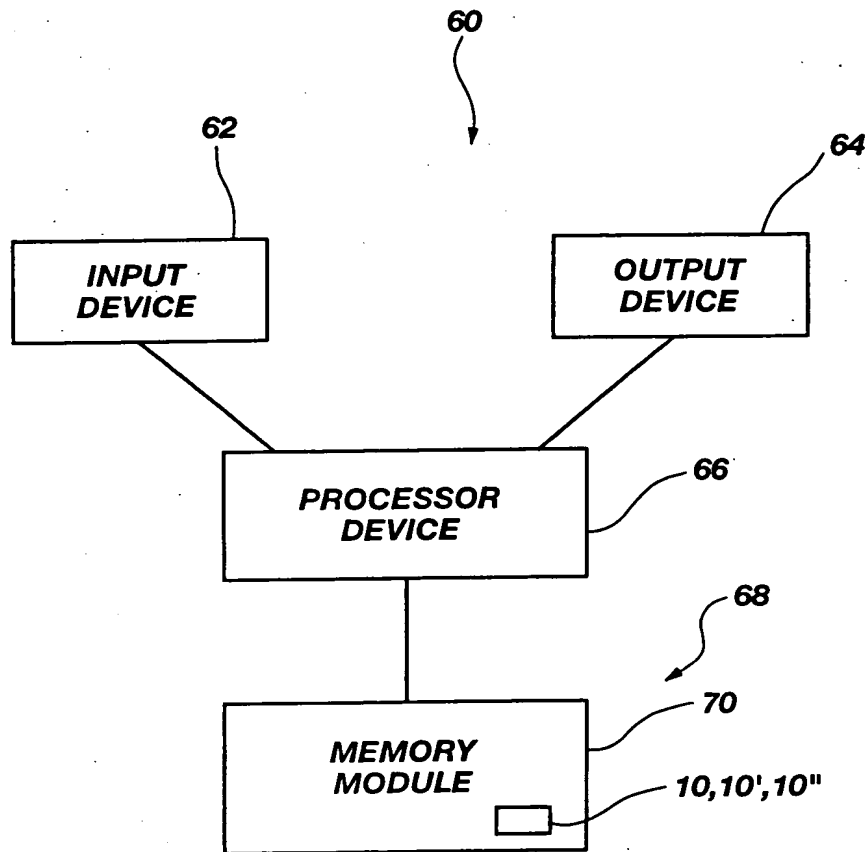


Fig. 6